

PCN Number:	20211006000.1		PCN Date:	October 07, 2021	
Title:	Qualification of RFAB as an additional Fab site option for select LBC7 devices				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Jan 7, 2022	Estimated Sample Availability:	Date provided at sample request.		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

Notification Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
MIHO8	LBC7	200 mm	RFAB	LBC7	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750




(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

UCC28056ADBVR	UCC28056BDBVR	UCC28056CDBVR	UCC28056CDBVT
UCC28056ADBVT	UCC28056BDBVT		

Qualification Report

Approve Date 17-Sep-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC28056ADBVR	Qual Device: UCC28056BDBVR	Qual Device: UCC28056CDBVR	QBS Product Reference: UCC28056DBV	QBS Process Reference: TP56C5712QPWP RQ1	QBS Package Reference: INA213AIDCKR	QBS Package Reference: TPS2553DBV
-	Power Cycling @ 25C	10K power up/down cycles	-	-	-	3/231/0	-	-	-
AC	Autoclave 121C	96 Hours	-	-	-	-	3/231/0	1/80/0	1/77/0
CDM	ESD - CDM	250 V	1/3/0	1/3/0	-	1/3/0	1/3/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/Pass	1/Pass	-	1/Pass	3/Pass	-	1/Pass
ELFR	Early Life Failure Rate, 150C	24 Hours	-	-	-	-	3/2400/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	-
HBM	ESD - HBM	1000 V	1/3/0	1/3/0	-	1/3/0	1/3/0	-	-
HTOL	Life Test, 150C	480 Hours	-	-	-	-	3/231/0	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	3/231/0	-	1/80/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	3/231/0	-	-
HTSL	High Temp Storage Bake 175C	500 Hours	-	-	-	-	1/45/0	-	-
LU	Latch-up (per JESD78)	125C	1/6/0	1/6/0	-	1/6/0	3/15/0	-	-
LU	Latch-up	125C	-	-	-	-	1/6/0	-	-
PD	Physical Dimensions	-	-	-	-	1/Pass	-	-	1/Pass

Type	Test Name / Condition	Duration	Qual Device: UCC28056ADBVR	Qual Device: UCC28056BDBVR	Qual Device: UCC28056CDBVR	QBS Product Reference: UCC28056DBV	QBS Process Reference: TP56C5712QPWP RQ1	QBS Package Reference: INA213AIDCKR	QBS Package Reference: TPS2553DBV
SD	Surface Mount Solderability	Pb Free Solder	-	-	-	-	-	1/22/0	1/22/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	1/77/0	3/231/0	1/77/0	1/77/0
WBP	Bond Pull	Wires	-	-	-	1/Pass	-	-	1/Pass
WBS	Bond Shear	Wires	-	-	-	1/Pass	-	-	1/Pass

- QBS: Qual By Similarity

- Qual Device UCC28056CDBVR is qualified at LEVEL1-260CG

- Qual Device UCC28056BDBVR is qualified at LEVEL1-260CG

- Qual Device UCC28056ADBVR is qualified at LEVEL1-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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